



Material Composition Declaration

EPC2018

Company Name	Efficient Power Conversion (EPC)	Issue Date:	11/11/2014
Contact Name:	Yanping Ma	Contact Title:	Dir. Q&R
Contact Phone:	(310) 615-0283	Contact Email:	yanping.ma@epc-co.com
Part Weight:	10.5 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	0.0000	0.00	89.17	0
	Silicon oxide	7631-86-9	9.1182	87.19		871854
	Silicon nitride	12033-89-5	0.0349	0.33		3336
	Gallium nitride	25617-97-4	0.0108	0.10		1037
	Aluminum	7429-90-5	0.0662	0.63		6332
	Aluminum nitride	24304-00-5	0.0683	0.65		6527
	Titanium	7440-32-6	0.0163	0.16		1556
	Titanium nitride	25583-20-4	0.0013	0.01		124
	Copper	7440-50-8	0.0058	0.06		552
	Tungsten	7440-33-7	0.0023	0.02		217
	Polyimide		0.0013	0.01		122
Under Bump Metal	Titanium	7440-32-6	0.0264	0.25	0.32	2527
	Nickel	7440-02-0	0.0017	0.02		166
	Vanadium	7440-62-2	0.0052	0.05		495
	Copper	7440-50-8	0.0003	0.00		25
Solder Bar	Tin	7440-31-5	0.0042	0.04	10.51	397
	Silver	7440-22-4	1.0337	9.88		98837
	Copper	7440-50-8	0.0617	0.59		5896
Sum in total:			10.5	100	100	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.